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PATENTS
112055-0040P1
17732-38560.001IN THE CLAIMS:

- 1 1. (currently amended) A die containing package comprising:
2 a die defining electrical die contacts,
3 a substrate defining first substrate contacts,
4 flattened electrical conductive balls attached to the die contacts and making
5 electrical connection thereto,
6 electrical conductive runs on the substrate connecting the first substrate contacts
7 to second substrate contacts,
8 electrically conductive wires with first ends making electrical connections to
9 the first substrate contacts, wherein the wires are formed to run substantially parallel to
10 the surface of the die, and wherein the other ends are horizontally attached to the flat-
11 tened balls. are arranged making electrical connections to the flattened electrical con-
12 ductive balls attached to the die contacts, and wherein the other ends remain substan-
13 tially parallel to the surface of the die as they make electrical connections to the flat-
14 tened electrical conductive balls.
- 1 2. Canceled.
- 1 3. (previously presented) The die containing package of claim 1 wherein the second
2 substrate contacts are located on the substrate opposite the first substrate contacts.
- 1 4. (previously presented) The die containing package of claim 1 wherein the second
2 substrate contacts are located on the substrate to accommodate a pin out different from
3 the die.

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1 5. (currently amended) A process for packaging a die comprising the steps of:
2 defining electrical die contacts,
3 defining a substrate with first substrate contacts,
4 flattening electrical conductive balls,
5 attaching the flattened electrically conductive balls to the die contacts,
6 forming electrical conductive runs on the substrate connecting the first substrate
7 contacts to second substrate contacts,
8 connecting electrically conductive wires to the first substrate contacts,
9 running the electrically conductive wires substantially parallel to the surface of
10 the die to the die contacts, and
11 ~~making electrical connections from~~ horizontally attaching the other ends of the
12 wires to the flattened electrical conductive balls thereby making electrical connections
13 therebetween attached to the die contacts, and wherein the other ends remain substan-
14 tially parallel to the surface of the die ~~as they make electrical connections to the flattened~~
15 ~~electrical conductive balls.~~

1 6. Canceled.

1 7. (previously presented) The process of claim 5 further comprising the step of locating
2 the second substrate contacts on the substrate opposite the first substrate contacts.

1 8. (previously presented) The process of claim 5 further comprising the step of locating
2 the second substrate contacts on the substrate to accommodate a pin out different from
3 the die.